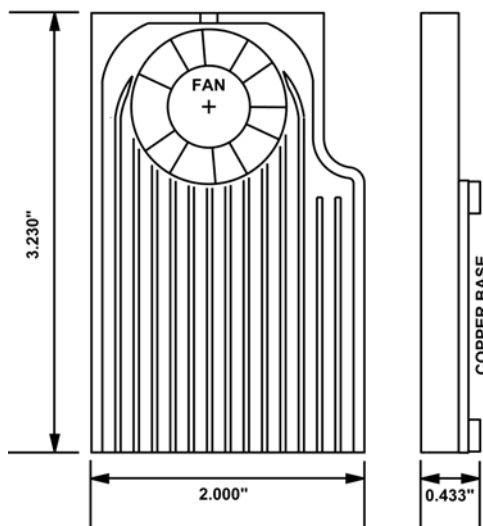


Low Profile Graphite Heat Sinks

New Thermal Solution for Electronic Cooling. Contact a Graftech representative to discuss your thermal needs or contact us at www.graftech.com. Graftech is dedicated to solving thermal problems, and can provide full design, rapid prototyping, and testing capabilities.

Outline Drawing



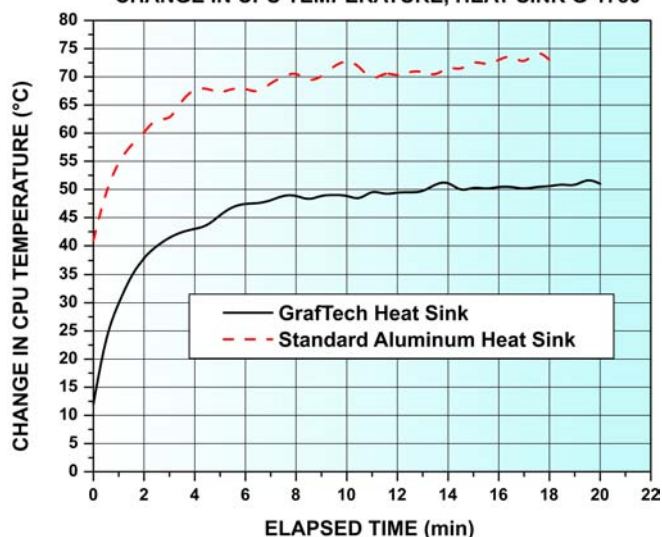
Elegant hybrid graphite/copper fan sink designs for low profile applications

- Custom designed for application using CFD and mechanical modeling
- Fan mounted into heat sink
- Graphite for light weight, high thermal conductivity
- Copper base plate for mechanical attachment



Part No. G-1780

CHASSIS THERMAL TEST
CHANGE IN CPU TEMPERATURE, HEAT SINK G-1780



This thermal data is shown in a 1U application with PIII/PIV processor operating at 20-25 watts. Internal chassis temperature is ~45°C. Internal fan-to-case clearance is 2 mm.

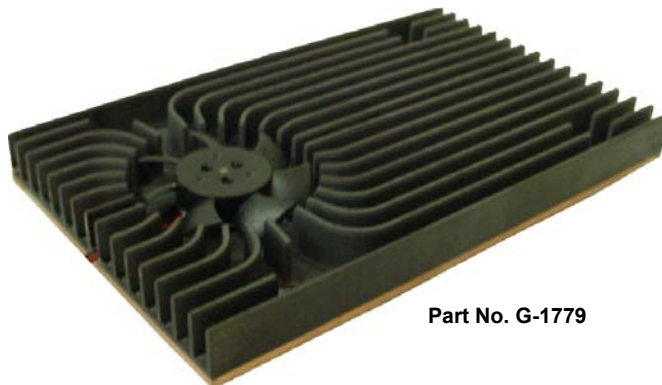
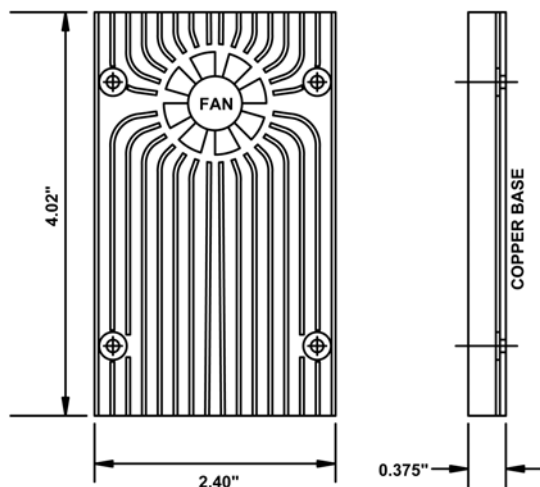
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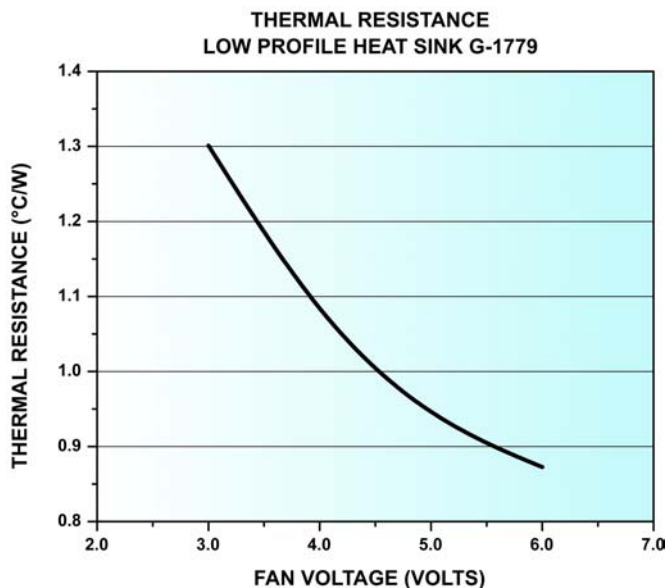


Low Profile Graphite Heat Sinks

Outline Drawing



Part No. G-1779



This thermal data is shown for a 21 Watt heat input with varying fan voltage. Ambient temperature is 25°C.

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